MICRO CERAMIC UHF RFID TAG

PRODUCT FAMILY DISPLAY

Ultra-small size | Thin package | Embedded identification

865 - 928 MHz

EPC Gen2 / ISO 18000-63

Product overview

An RFID IC, conductive silver paste and alumina-glass composite ceramic come together in a compact package for embedded identification.



Key features

01 **Ultra-small footprint**
Down to 1.20 x 1.20 x 0.70 mm

02 **0.70 mm thin package**
Nominal maximum thickness

03 **Composite ceramic body**
Alumina-glass composite ceramic

04 **Multiple IC platforms**
M830 / R6-P / U9 / U8

Available size series

Seven footprint options. Package thickness: 0.70 mm nominal.

1. 1.20 x 1.20 x 0.70 mm
2. 1.20 x 2.00 x 0.70 mm
3. 2.00 x 2.00 x 0.70 mm
4. 2.50 x 2.50 x 0.70 mm
5. 3.00 x 3.00 x 0.70 mm
6. 5.00 x 5.00 x 0.70 mm
7. 7.00 x 7.00 x 0.70 mm

IC and protocol platform

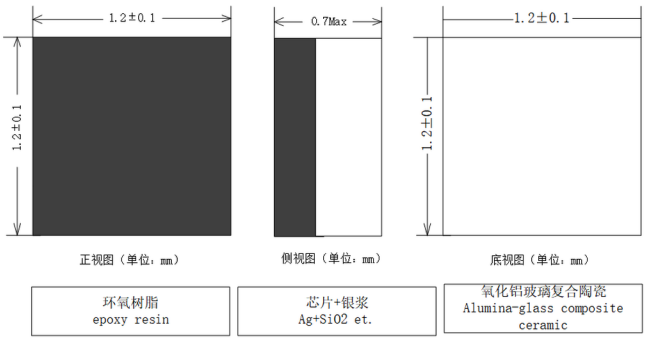
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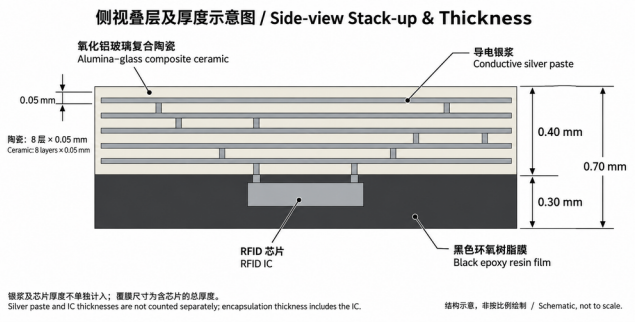
Typical use cases

Precision traceability | Small asset management | Embedded identification

Package structure and thickness

Reference drawings from the supplied technical materials.





Note: Confirm final dimensions, materials and IC compatibility against the released specification and sample qualification.